



2823
IFW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Aron T. Lunde

Application No.: 10/053,963

Filed: January 22, 2002

For: A DIE ASSEMBLY AND METHOD
FOR FORMING A DIE ON A
WAFER

§
§
§
§
§
§
§
§
§

Group Art Unit: 2823

Examiner: Nguyen, Khiem D.

Atty. Docket: MICS:0214/FLE/MAN/EUB
01-0596

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

CERTIFICATE OF MAILING
37 C.F.R. 1.8

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on the date below:

May 2, 2007

Date

L. Lee Eubanks IV

**AMENDMENT AND RESPONSE TO
OFFICE ACTION MAILED FEBRUARY 2, 2007**

Dear Sir:

In response to the Office Action mailed on February 2, 2007, Applicant respectfully requests reconsideration of the present application in view of the following amendments and remarks.